

# NCP4682, NCP4685

## 150 mA, Ultra Low Supply Current, Low Dropout Regulator

The NCP4682 and NCP4685 are CMOS Low Dropout Linear voltage regulators with 150 mA output current capability. The devices have high output voltage accuracy, a 1  $\mu$ A (typ.) ultra low supply current and high ripple rejection. Current fold-back protection is integrated in the devices to protect against over current and short current conditions. A Chip Enable (NCP4682 only) function is included to save power by further lowering supply current, which is advantageous for battery powered applications. The NCP4685 is optimized for the lowest quiescent current possible in applications where the device is always on.

### Features

- Operating Input Voltage Range: 1.70 V to 5.25 V
- Output Voltage Range: 1.2 V to 3.3 V (available in 0.1 V steps)
- Output Voltage Accuracy:  $\pm 0.8\%$
- Excellent Output Voltage Temperature Coefficient :  $\pm 40$  ppm/ $^{\circ}$ C
- Supply Current: 1.0  $\mu$ A (excluding CE pull down current)
- Standby Current: 0.1  $\mu$ A
- Dropout Voltage: 0.24 V ( $I_{OUT} = 150$  mA,  $V_{OUT} = 2.8$  V)
- Line Regulation: 0.02%/V Typ.
- Stable with Ceramic Capacitors: 0.1  $\mu$ F or more
- Current Fold Back Protection
- Available in UDFN4 1.0 x 1.0 mm, SC-82AB, SOT23 Packages
- These are Pb-Free Devices

### Typical Applications

- Battery-Powered Equipment
- Networking and Communication Equipment
- Cameras, DVRs, STB and Camcorders
- Home Appliances

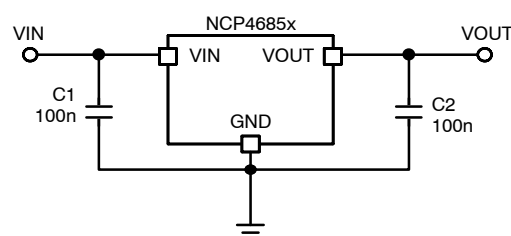
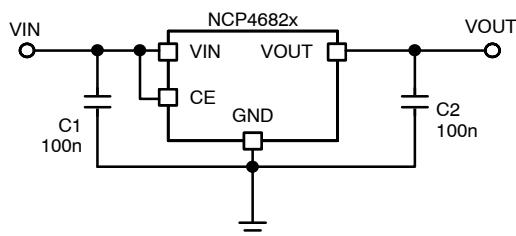


Figure 1. Typical Application Schematics



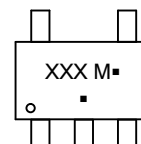
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<http://onsemi.com>

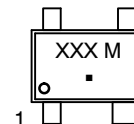
### MARKING DIAGRAMS



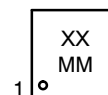
**SOT-23-5  
CASE 1212**



**SC-82AB  
CASE 419C**



**UDFN4  
CASE 517BR**



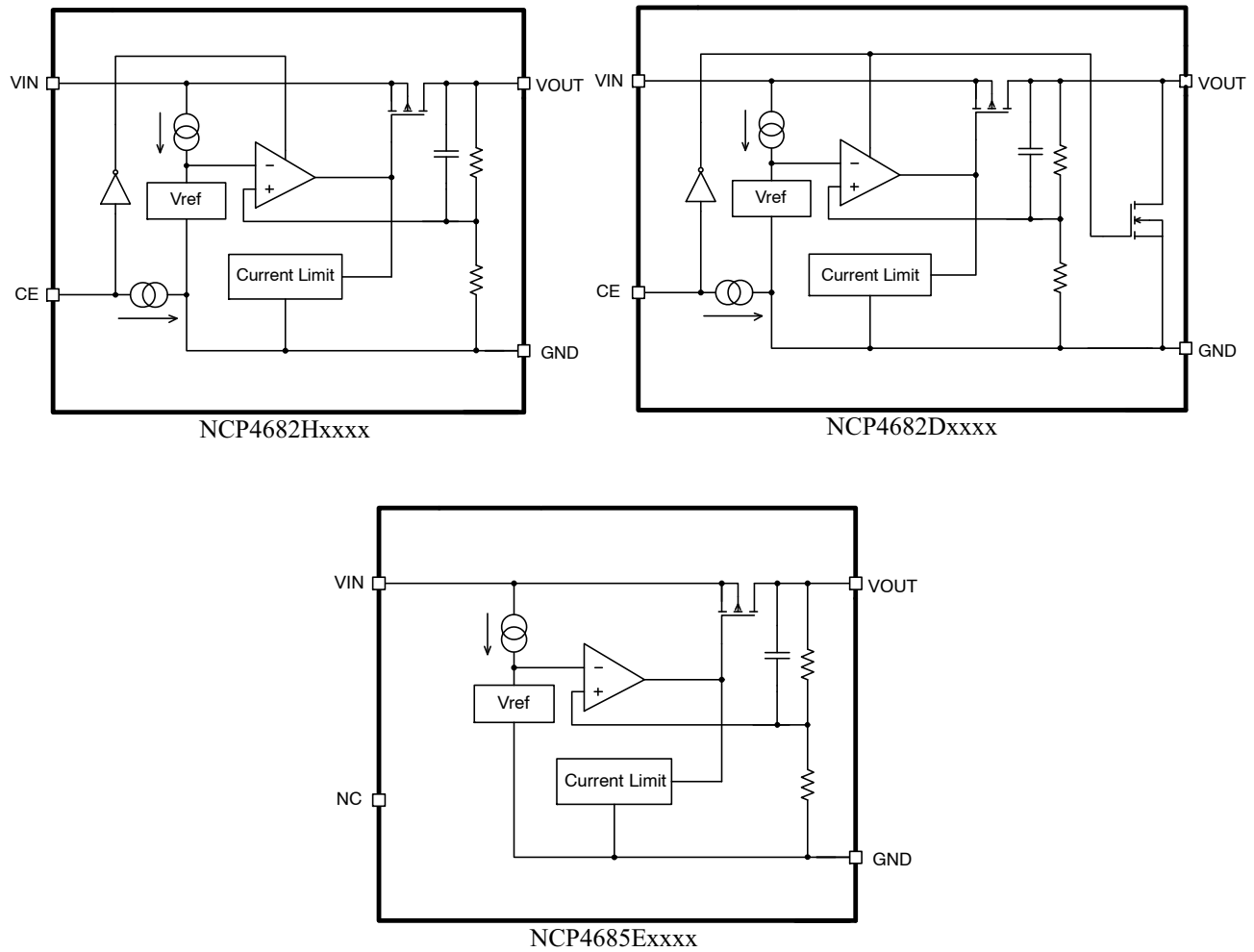
XXX, XX = Specific Device Code  
M, MM = Date Code  
▪ = Pb-Free Package

(\*Note: Microdot may be in either location)

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 19 of this data sheet.

## NCP4682, NCP4685



**Figure 2. Simplified Schematic Block Diagram**

### PIN FUNCTION DESCRIPTION

| Pin No.<br>UDFN1010* | Pin No.<br>SC-82AB | Pin No.<br>SOT23 | Pin Name         | Description                                  |
|----------------------|--------------------|------------------|------------------|----------------------------------------------|
| 1                    | 3                  | 5                | V <sub>OUT</sub> | Output pin                                   |
| 2                    | 2                  | 2                | GND              | Ground                                       |
| 3                    | 1                  | 3                | CE/NC            | Chip enable pin (Active "H") / No connection |
| 4                    | 4                  | 1                | V <sub>IN</sub>  | Input pin                                    |
| –                    | –                  | 4                | NC               | No connection                                |

\*Tab is GND level. (They are connected to the reverse side of this IC.)

The tab is better to be connected to the GND, but leaving it open is also acceptable.

### ABSOLUTE MAXIMUM RATINGS

| Rating                 | Symbol           | Value                         | Unit |
|------------------------|------------------|-------------------------------|------|
| Input Voltage (Note 1) | V <sub>IN</sub>  | 6.0                           | V    |
| Output Voltage         | V <sub>OUT</sub> | –0.3 to V <sub>IN</sub> + 0.3 | V    |
| Chip Enable Input      | V <sub>CE</sub>  | 6.0                           | V    |
| Output Current         | I <sub>OUT</sub> | 200                           | mA   |

# NCP4682, NCP4685

## ABSOLUTE MAXIMUM RATINGS

| Rating                                    | Symbol      | Value      | Unit |
|-------------------------------------------|-------------|------------|------|
| Power Dissipation UDFN1010                | $P_D$       | 400        | mW   |
| Power Dissipation SC-82AB                 |             | 380        |      |
| Power Dissipation SOT23                   |             | 420        |      |
| Junction Temperature                      | $T_J$       | -40 to 150 | °C   |
| Storage Temperature                       | $T_{STG}$   | -55 to 125 | °C   |
| ESD Capability, Human Body Model (Note 2) | $ESD_{HBM}$ | 2000       | V    |
| ESD Capability, Machine Model (Note 2)    | $ESD_{MM}$  | 200        | V    |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Refer to ELECTRICAL CHARACTERISTICS and APPLICATION INFORMATION for Safe Operating Area.
2. This device series incorporates ESD protection and is tested by the following methods:  
 ESD Human Body Model tested per AEC-Q100-002 (EIA/JESD22-A114)  
 ESD Machine Model tested per AEC-Q100-003 (EIA/JESD22-A115)  
 Latchup Current Maximum Rating tested per JEDEC standard: JESD78.

## THERMAL CHARACTERISTICS

| Rating                                                                            | Symbol          | Value | Unit |
|-----------------------------------------------------------------------------------|-----------------|-------|------|
| Thermal Characteristics, UDFN 1.0 x 1.0 mm<br>Thermal Resistance, Junction-to-Air | $R_{\theta JA}$ | 250   | °C/W |
| Thermal Characteristics, SOT23<br>Thermal Resistance, Junction-to-Air             | $R_{\theta JA}$ | 238   | °C/W |
| Thermal Characteristics, SC-82AB<br>Thermal Resistance, Junction-to-Air           | $R_{\theta JA}$ | 263   | °C/W |

## ELECTRICAL CHARACTERISTICS

-40°C ≤  $T_A$  ≤ 85°C;  $V_{IN} = V_{OUT(NOM)} + 1$  V or 2.5 V, whichever is greater;  $I_{OUT} = 1$  mA,  $C_{IN} = C_{OUT} = 0.1$  μF, unless otherwise noted.  
 Typical values are at  $T_A = +25$ °C.

| Parameter                        | Test Conditions                           |                             | Symbol                        | Min    | Typ  | Max    | Unit   |
|----------------------------------|-------------------------------------------|-----------------------------|-------------------------------|--------|------|--------|--------|
| Operating Input Voltage          | (Note 3)                                  |                             | $V_{IN}$                      | 1.70   |      | 5.25   | V      |
| Output Voltage                   | $T_A = +25$ °C                            | $V_{OUT} \geq 2.0$ V        | $V_{OUT}$                     | x0.992 |      | x1.008 | V      |
|                                  |                                           | $V_{OUT} < 2.0$ V           |                               | -16    |      | 16     | mV     |
|                                  | -40°C ≤ $T_A$ ≤ 85°C                      | $V_{OUT} \geq 2.0$ V        |                               | x0.985 |      | x1.015 | V      |
|                                  |                                           | $V_{OUT} < 2.0$ V           |                               | -30    |      | 30     | mV     |
| Output Voltage Temp. Coefficient | -40°C ≤ $T_A$ ≤ 85°C                      |                             | $\Delta V_{OUT} / \Delta T_A$ |        | ±40  |        | ppm/°C |
| Line Regulation                  | $V_{OUT(NOM)} + 0.5$ V ≤ $V_{IN}$ ≤ 5.0 V |                             | $Line_{Reg}$                  |        | 0.02 | 0.10   | %/V    |
| Load Regulation                  | $I_{OUT} = 1$ mA to 150 mA                |                             | $Load_{Reg}$                  |        | 10   | 20     | mV     |
| Dropout Voltage                  | $I_{OUT} = 150$ mA                        | $1.2$ V ≤ $V_{OUT} < 1.5$ V | $V_{DO}$                      |        | 0.76 | 1.05   | V      |
|                                  |                                           | $1.5$ V ≤ $V_{OUT} < 1.7$ V |                               |        | 0.53 | 0.80   |        |
|                                  |                                           | $1.7$ V ≤ $V_{OUT} < 2.0$ V |                               |        | 0.44 | 0.65   |        |
|                                  |                                           | $2.0$ V ≤ $V_{OUT} < 2.5$ V |                               |        | 0.34 | 0.50   |        |
|                                  |                                           | $2.5$ V ≤ $V_{OUT} < 2.8$ V |                               |        | 0.28 | 0.40   |        |
|                                  |                                           | $2.8$ V ≤ $V_{OUT} < 3.3$ V |                               |        | 0.24 | 0.32   |        |
| Output Current                   |                                           |                             | $I_{OUT}$                     | 150    |      |        | mA     |
| Short Current Limit              | $V_{OUT} = 0$ V                           |                             | $I_{SC}$                      |        | 40   |        | mA     |
| Quiescent Current                |                                           |                             | $I_Q$                         |        | 1.0  | 1.5    | μA     |

## NCP4682, NCP4685

### ELECTRICAL CHARACTERISTICS

$-40^{\circ}\text{C} \leq T_A \leq 85^{\circ}\text{C}$ ;  $V_{IN} = V_{OUT(NOM)} + 1\text{ V}$  or  $2.5\text{ V}$ , whichever is greater;  $I_{OUT} = 1\text{ mA}$ ,  $C_{IN} = C_{OUT} = 0.1\text{ }\mu\text{F}$ , unless otherwise noted. Typical values are at  $T_A = +25^{\circ}\text{C}$ .

| Parameter                                  | Test Conditions                                                                                                                                | Symbol     | Min | Typ | Max | Unit                |
|--------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------|------------|-----|-----|-----|---------------------|
| Standby Current                            | $V_{CE} = 0\text{ V}$ , $T_A = 25^{\circ}\text{C}$ , NCP4682 only                                                                              | $I_{STB}$  |     | 0.1 | 1.0 | $\mu\text{A}$       |
| CE Pin Threshold Voltage<br>(NCP4682 only) | CE Input Voltage "H"                                                                                                                           | $V_{CEH}$  | 1.5 |     |     | V                   |
|                                            | CE Input Voltage "L"                                                                                                                           | $V_{CEL}$  |     |     | 0.3 |                     |
| CE Pull Down Current                       | NCP4682 only                                                                                                                                   | $I_{CEPD}$ |     | 0.3 |     | $\mu\text{A}$       |
| Power Supply Rejection Ratio               | $V_{IN} = 2.2\text{ V}$ , $V_{OUT} = 1.2\text{ V}$ , $\Delta V_{IN} = 0.2\text{ V}_{pk-pk}$ ,<br>$I_{OUT} = 30\text{ mA}$ , $f = 1\text{ kHz}$ | PSRR       |     | 30  |     | dB                  |
| Output Noise Voltage                       | $f = 10\text{ Hz}$ to $100\text{ kHz}$ , $I_{OUT} = 30\text{ mA}$ , $V_{OUT} = 1.2\text{ V}$ , $V_{IN} = 2.2\text{ V}$                         | $V_N$      |     | 70  |     | $\mu\text{V}_{rms}$ |
| Low Output Nch Tr. On Resistance           | $V_{IN} = 4\text{ V}$ , $V_{CE} = 0\text{ V}$ , NCP4682D only                                                                                  | $R_{LOW}$  |     | 30  |     | $\Omega$            |

3. The maximum Input Voltage of the Electrical Characteristics is 5.25 V. In case of exceeding this specification, the IC must be operated in condition that the Input Voltage is up to 5.50 V and total operation time is within 500 hours.

TYPICAL CHARACTERISTICS

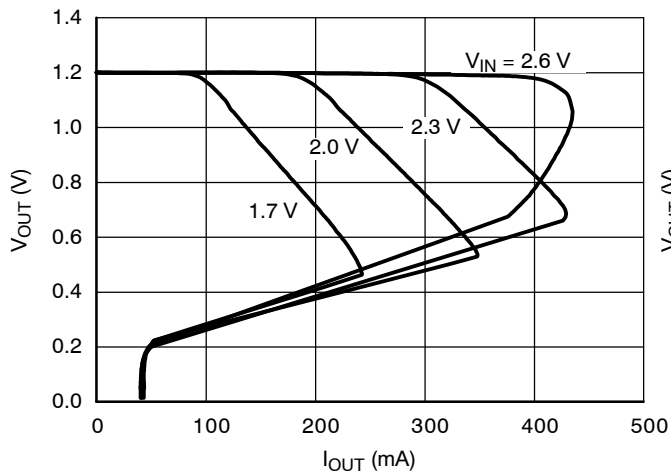


Figure 3. Output Voltage vs. Output Current  
1.2 V Version ( $T_J = 25^\circ\text{C}$ )

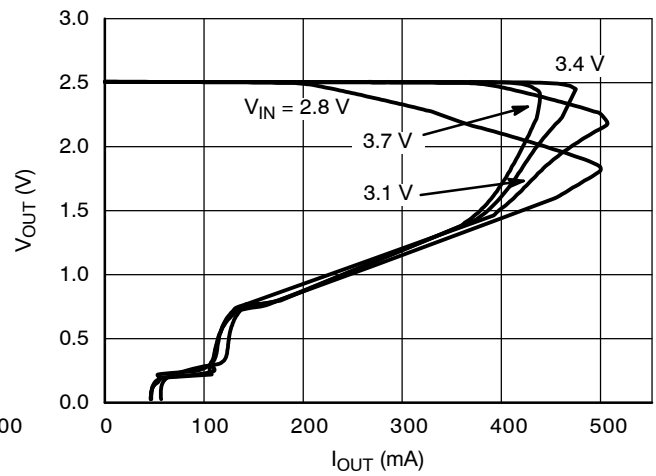


Figure 4. Output Voltage vs. Output Current  
2.5 V Version ( $T_J = 25^\circ\text{C}$ )

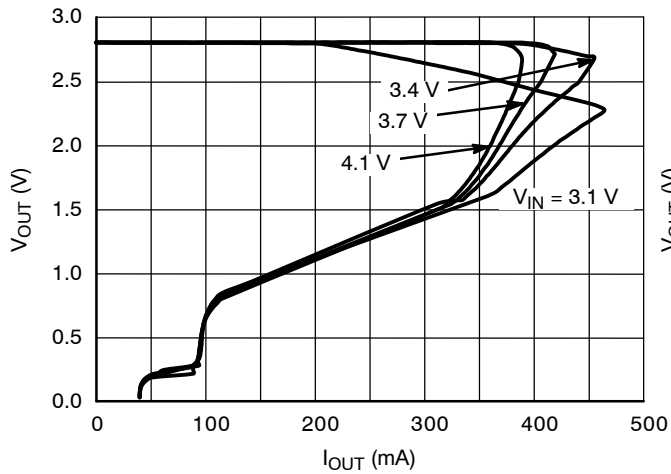


Figure 5. Output Voltage vs. Output Current  
2.8 V Version ( $T_J = 25^\circ\text{C}$ )

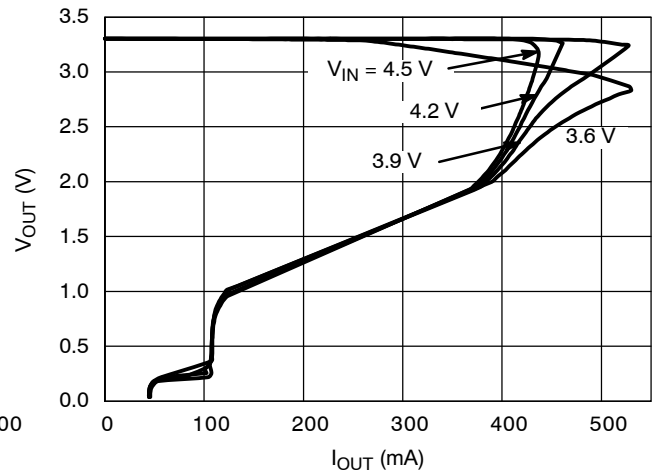


Figure 6. Output Voltage vs. Output Current  
3.3 V Version ( $T_J = 25^\circ\text{C}$ )

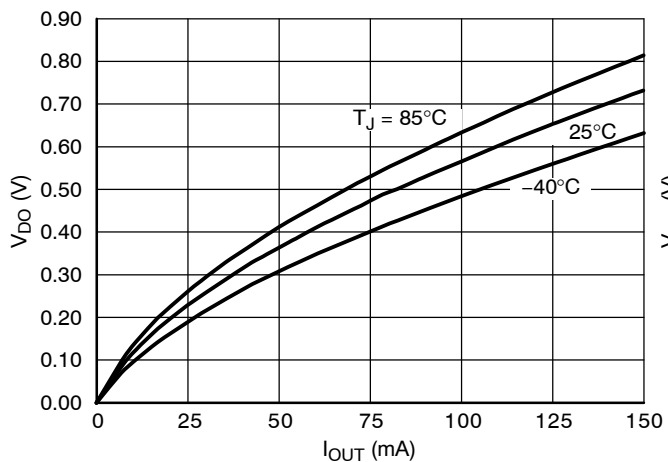


Figure 7. Dropout Voltage vs. Output Current  
1.2 V Version

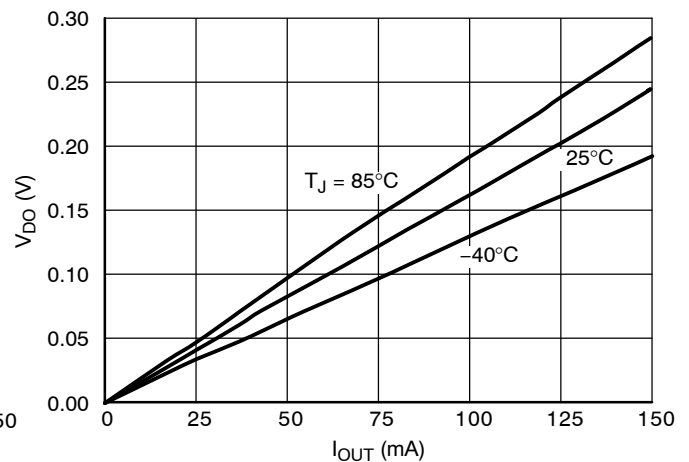


Figure 8. Dropout Voltage vs. Output Current  
2.5 V Version

TYPICAL CHARACTERISTICS

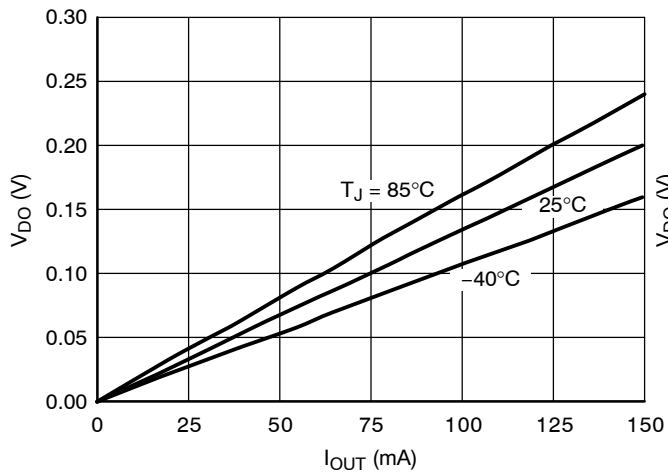


Figure 9. Dropout Voltage vs. Output Current  
2.8 V Version

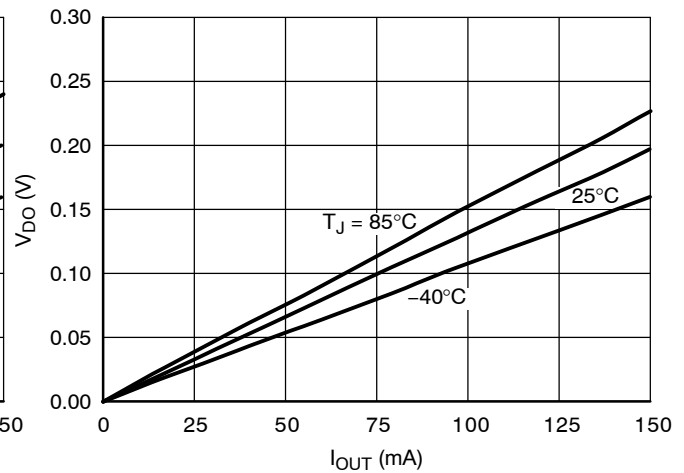


Figure 10. Dropout Voltage vs. Output Current  
3.3 V Version

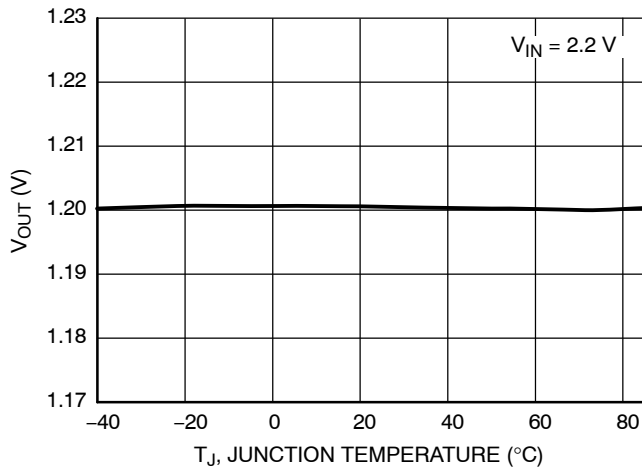


Figure 11. Output Voltage vs. Temperature,  
1.2 V Version

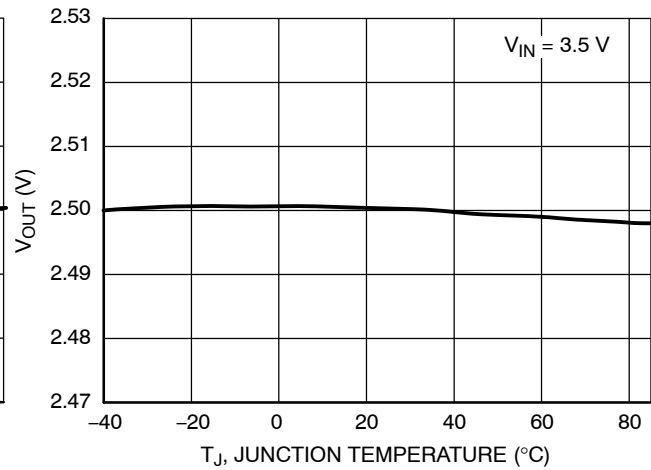


Figure 12. Output Voltage vs. Temperature,  
2.5 V Version

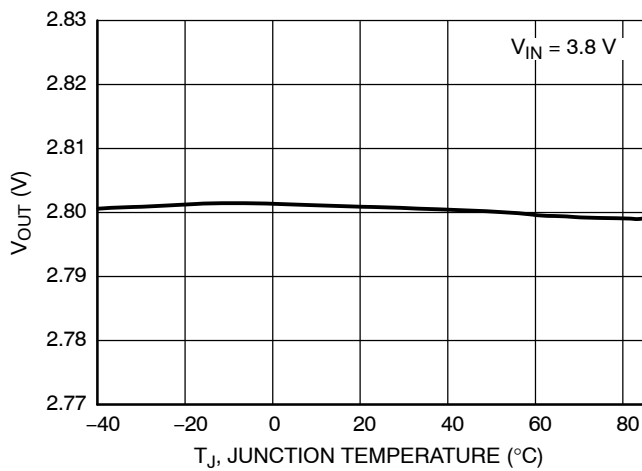


Figure 13. Output Voltage vs. Temperature,  
2.8 V Version

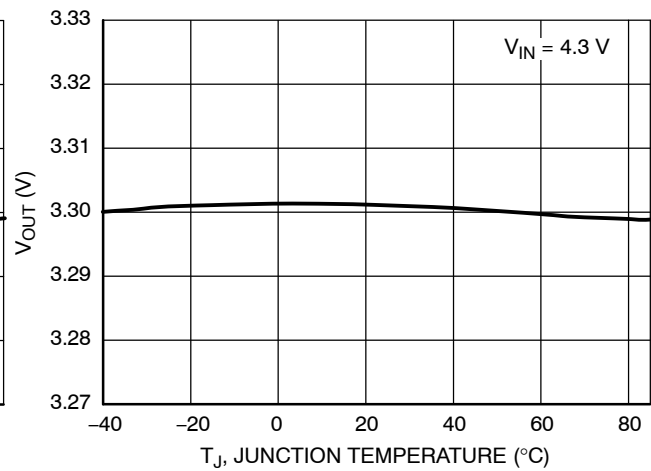


Figure 14. Output Voltage vs. Temperature,  
3.3 V Version

TYPICAL CHARACTERISTICS

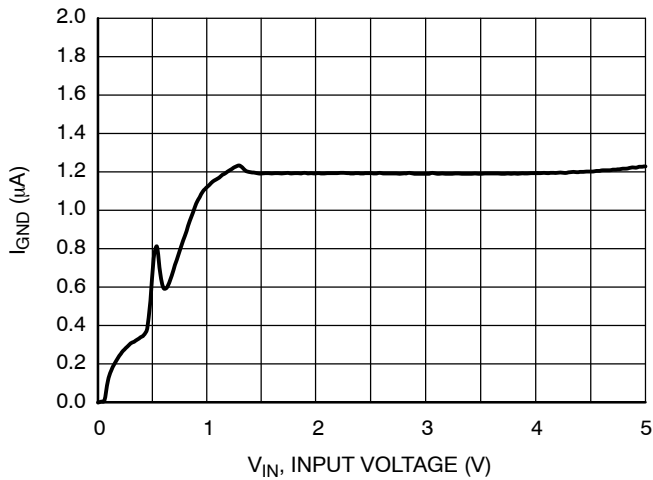


Figure 15. Supply Current vs. Input Voltage, 1.2 V Version

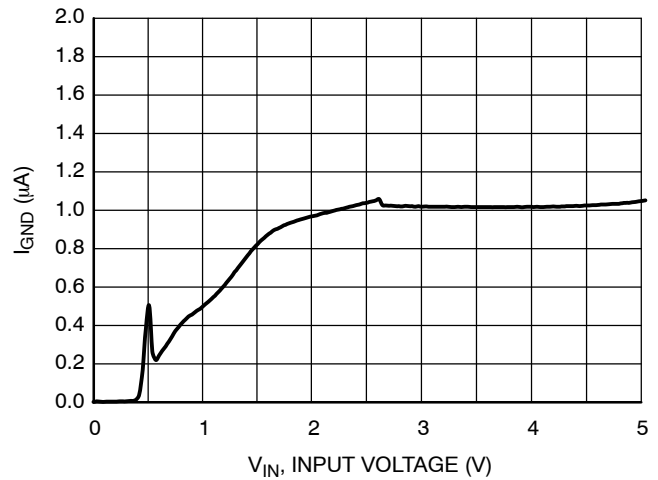


Figure 16. Supply Current vs. Input Voltage, 2.5 V Version

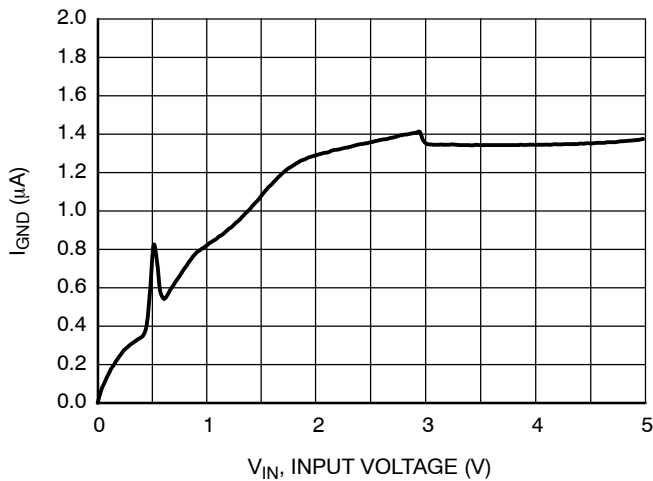


Figure 17. Supply Current vs. Input Voltage, 2.8 V Version

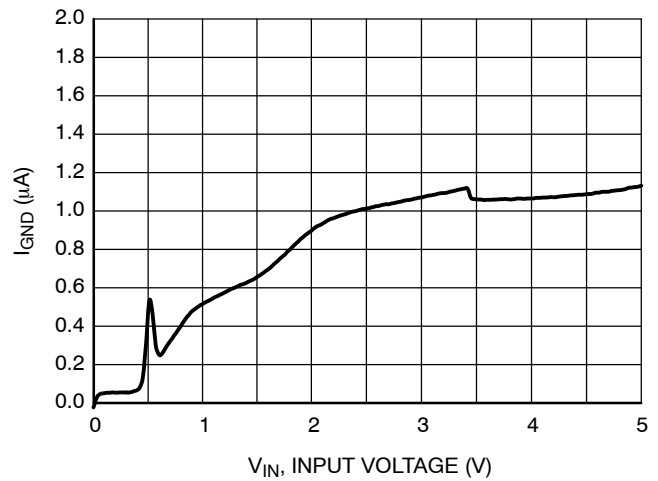


Figure 18. Supply Current vs. Input Voltage, 3.3 V Version

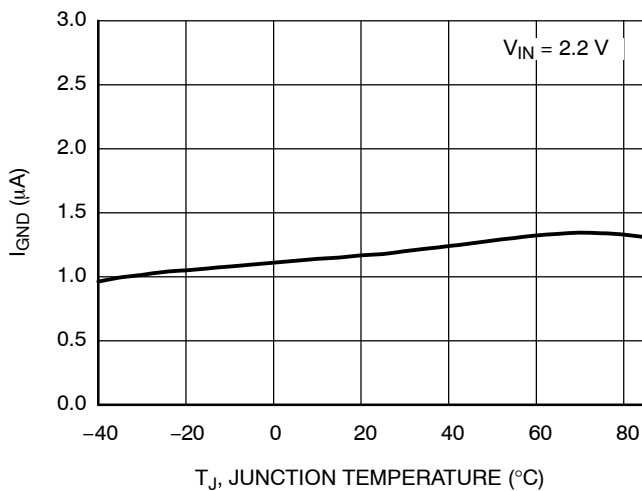


Figure 19. Supply Current vs. Temperature, 1.2 V Version

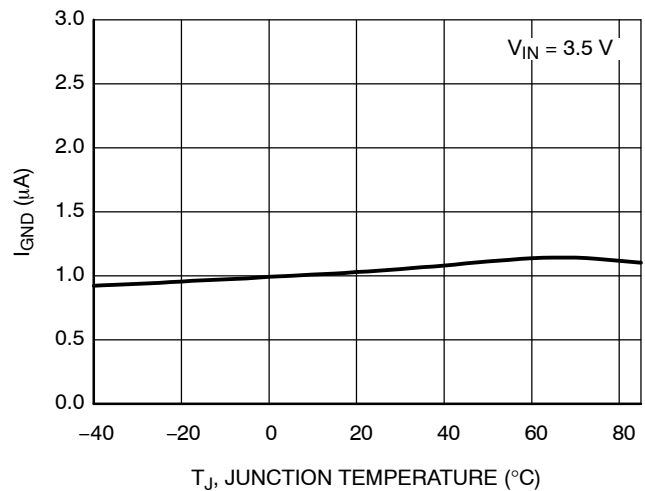


Figure 20. Supply Current vs. Temperature, 2.5 V Version

TYPICAL CHARACTERISTICS

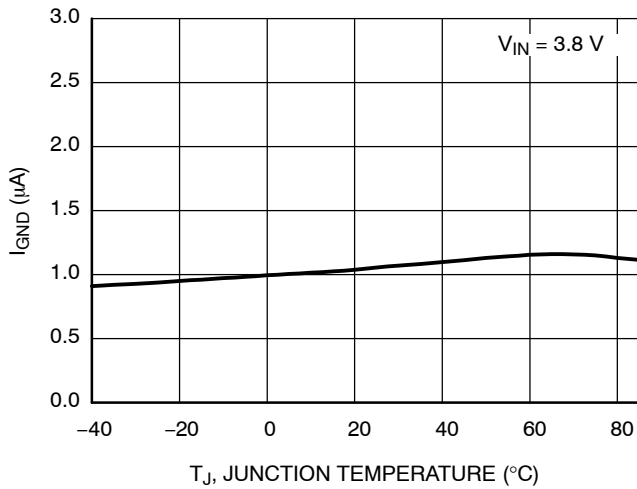


Figure 21. Supply Current vs. Temperature, 2.8 V Version

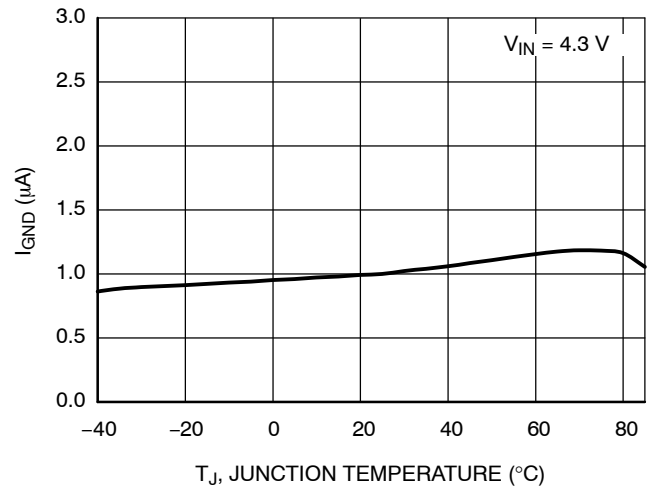


Figure 22. Supply Current vs. Temperature, 3.3 V Version

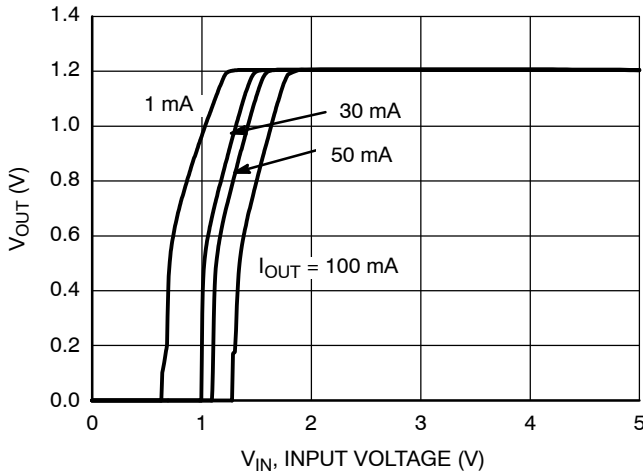


Figure 23. Output Voltage vs. Input Voltage, 1.2 V Version

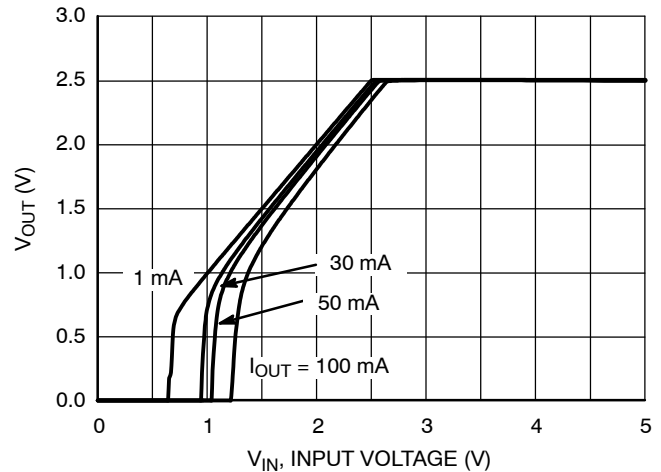


Figure 24. Output Voltage vs. Input Voltage, 2.5 V Version

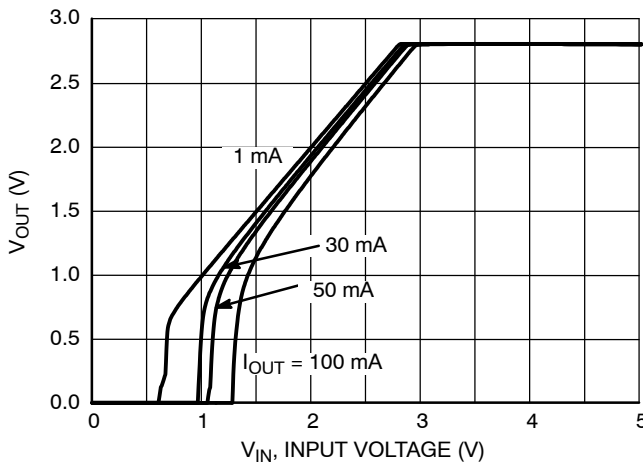


Figure 25. Output Voltage vs. Input Voltage, 2.8 V Version

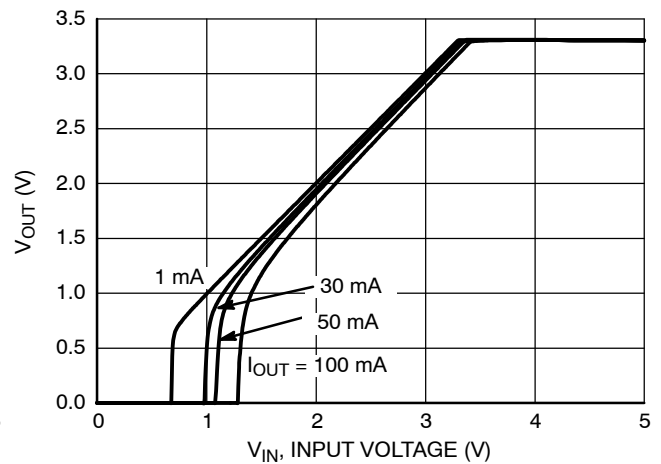


Figure 26. Output Voltage vs. Input Voltage, 3.3 V Version

TYPICAL CHARACTERISTICS

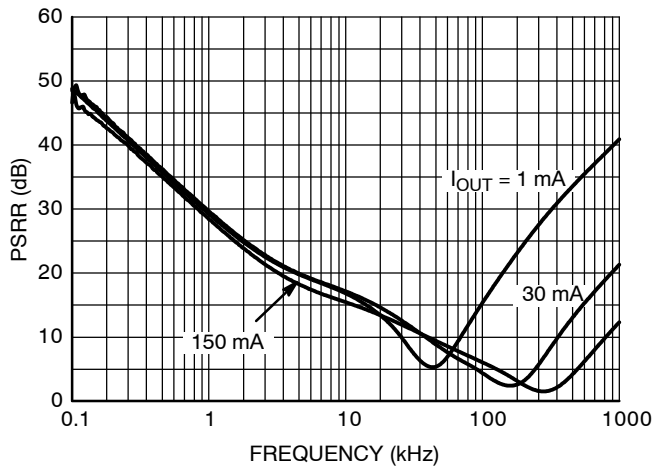


Figure 27. PSRR, 1.2 V Version,  $V_{IN} = 2.2$  V

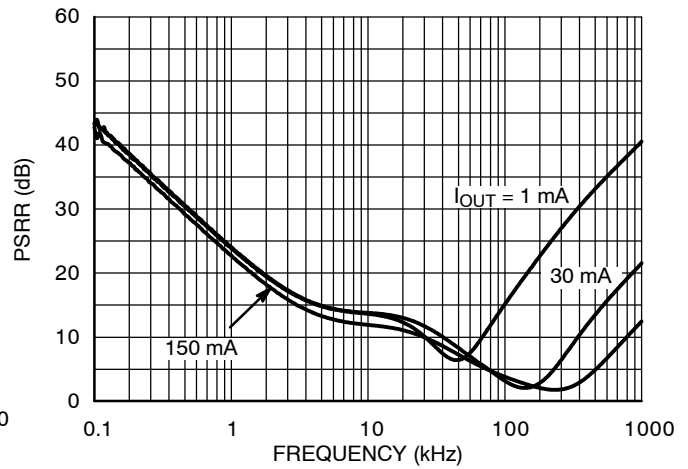


Figure 28. PSRR, 2.5 V Version,  $V_{IN} = 3.5$  V

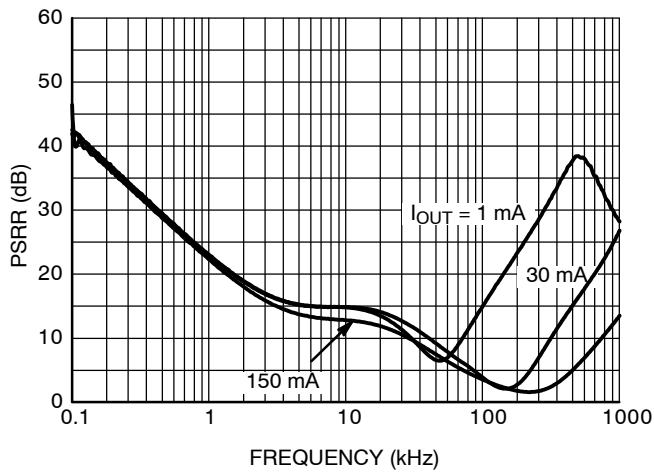


Figure 29. PSRR, 2.8 V Version,  $V_{IN} = 3.8$  V

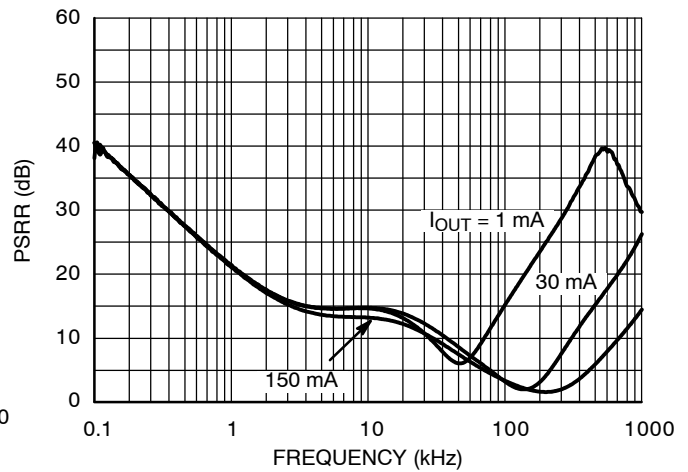


Figure 30. PSRR, 3.3 V Version,  $V_{IN} = 4.3$  V

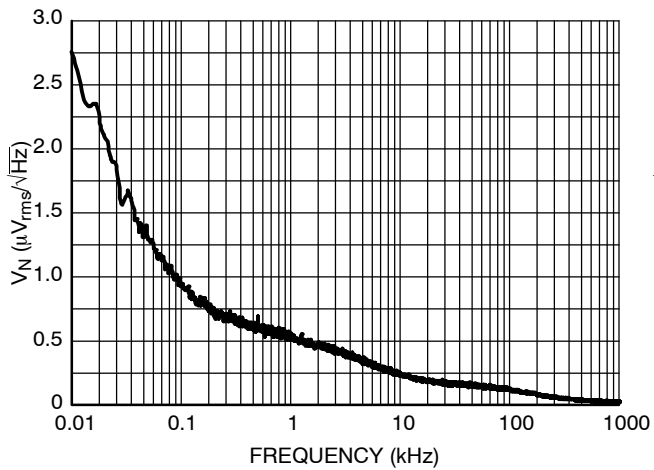


Figure 31. Output Voltage Noise, 1.2 V Version,  $V_{IN} = 2.2$  V,  $I_{OUT} = 30$  mA

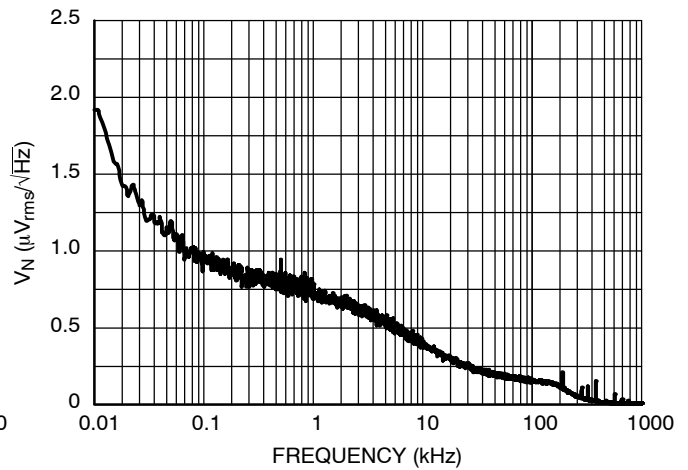


Figure 32. Output Voltage Noise, 2.5 V Version,  $V_{IN} = 3.5$  V,  $I_{OUT} = 30$  mA

TYPICAL CHARACTERISTICS

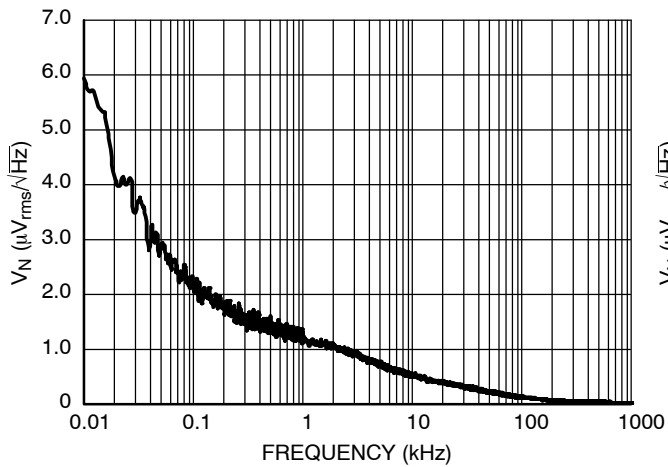


Figure 33. Output Voltage Noise, 2.8 V Version,  
 $V_{\text{IN}} = 3.8 \text{ V}$ ,  $I_{\text{OUT}} = 30 \text{ mA}$

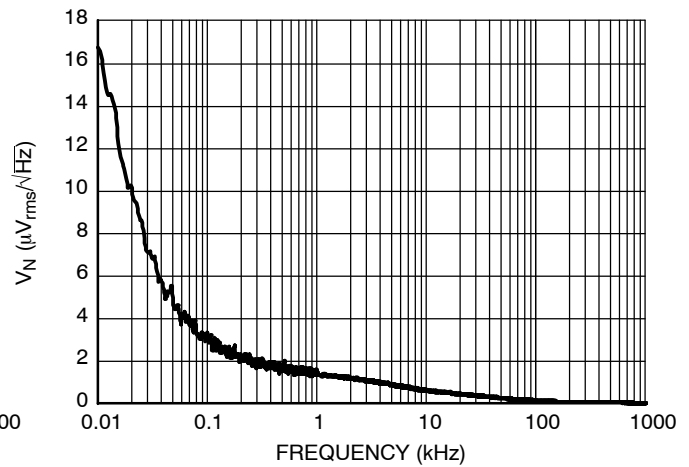


Figure 34. Output Voltage Noise, 3.3 V Version,  
 $V_{\text{IN}} = 4.3 \text{ V}$ ,  $I_{\text{OUT}} = 30 \text{ mA}$

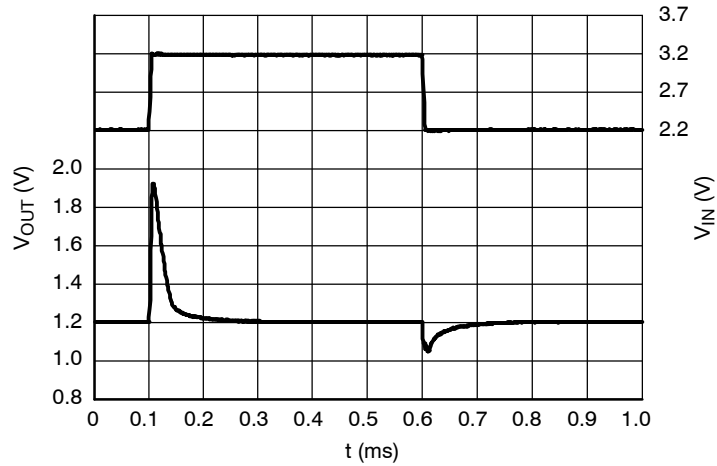


Figure 35. Line Transients, 1.2 V Version,  
 $t_R = t_F = 5 \mu\text{s}$ ,  $I_{\text{OUT}} = 30 \text{ mA}$

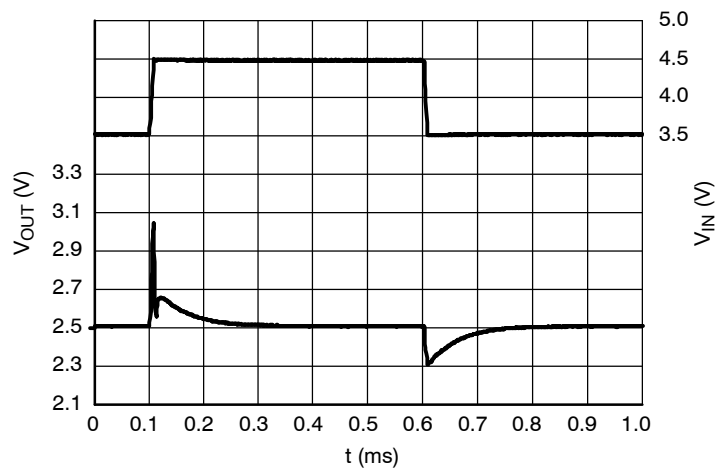


Figure 36. Line Transients, 2.5 V Version,  
 $t_R = t_F = 5 \mu\text{s}$ ,  $I_{\text{OUT}} = 30 \text{ mA}$

TYPICAL CHARACTERISTICS

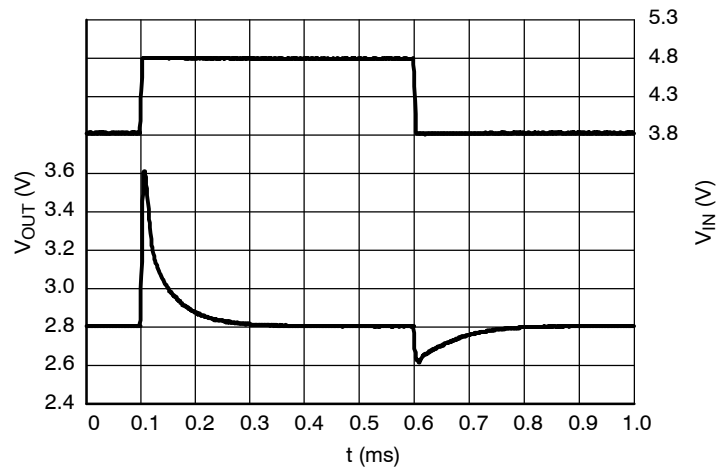


Figure 37. Line Transients, 2.8 V Version,  
 $t_R = t_F = 5 \mu s$ ,  $I_{OUT} = 30$  mA

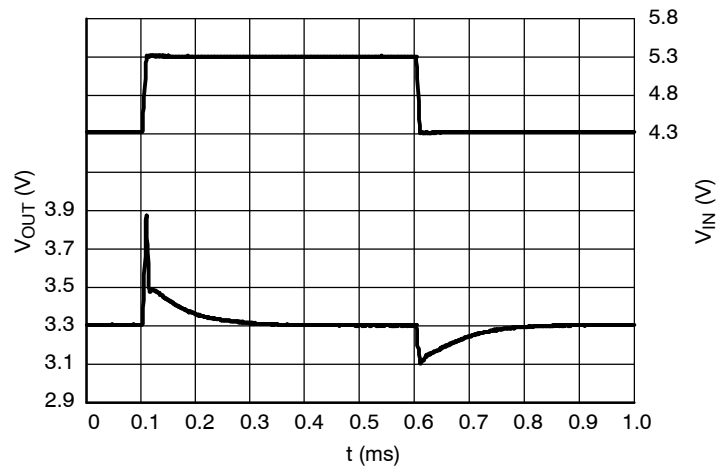


Figure 38. Line Transients, 3.3 V Version,  
 $t_R = t_F = 5 \mu s$ ,  $I_{OUT} = 30$  mA

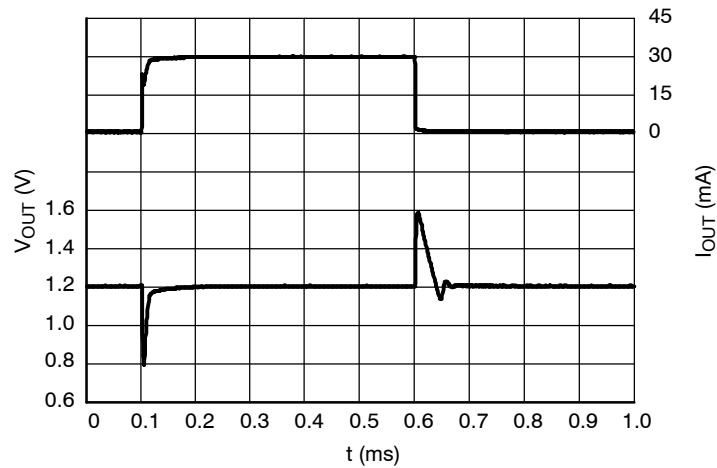
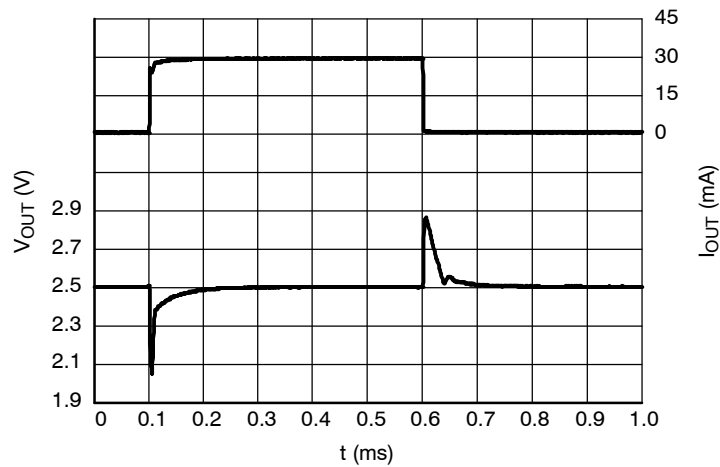
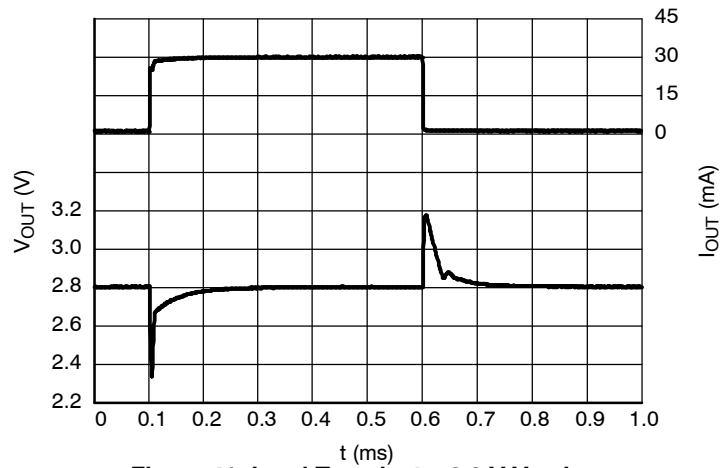


Figure 39. Load Transients, 1.2 V Version,  
 $I_{OUT} = 1 - 30$  mA,  $t_R = t_F = 0.5 \mu s$ ,  $V_{IN} = 2.2$  V

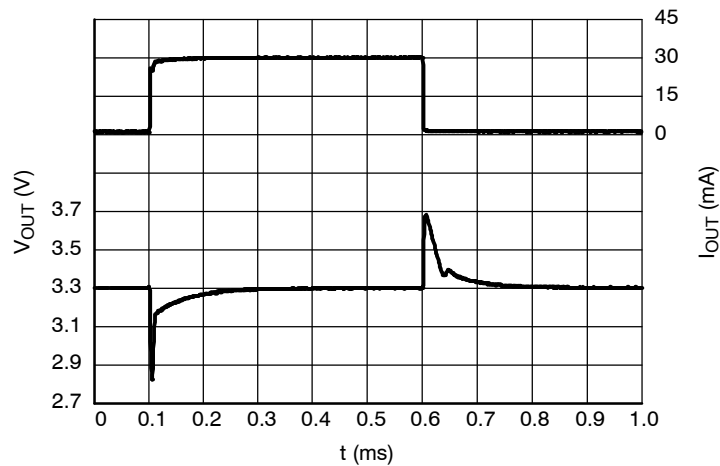
TYPICAL CHARACTERISTICS



**Figure 40. Load Transients, 2.5 V Version,**  
 $I_{OUT} = 1 - 30$  mA,  $t_R = t_F = 0.5$   $\mu$ s,  $V_{IN} = 3.5$  V

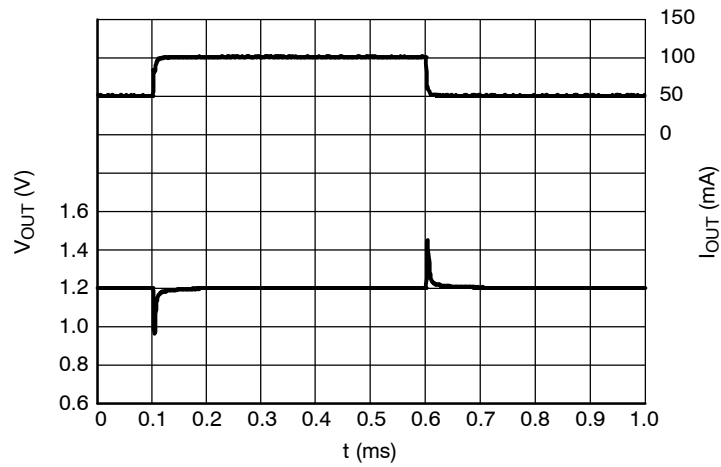


**Figure 41. Load Transients, 2.8 V Version,**  
 $I_{OUT} = 1 - 30$  mA,  $t_R = t_F = 0.5$   $\mu$ s,  $V_{IN} = 3.8$  V

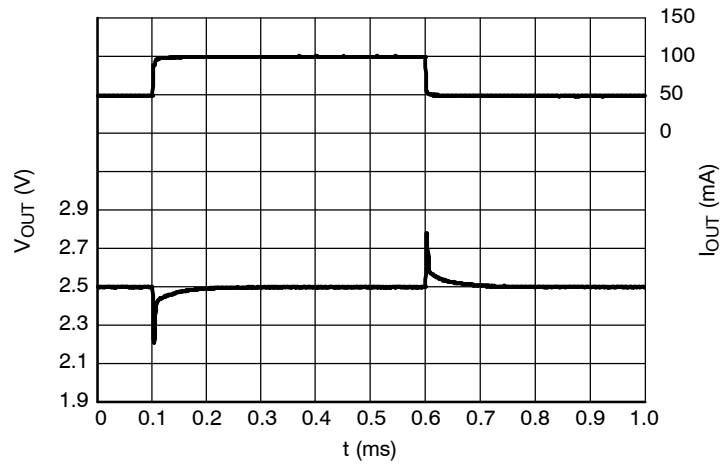


**Figure 42. Load Transients, 3.3 V Version,**  
 $I_{OUT} = 1 - 30$  mA,  $t_R = t_F = 0.5$   $\mu$ s,  $V_{IN} = 4.3$  V

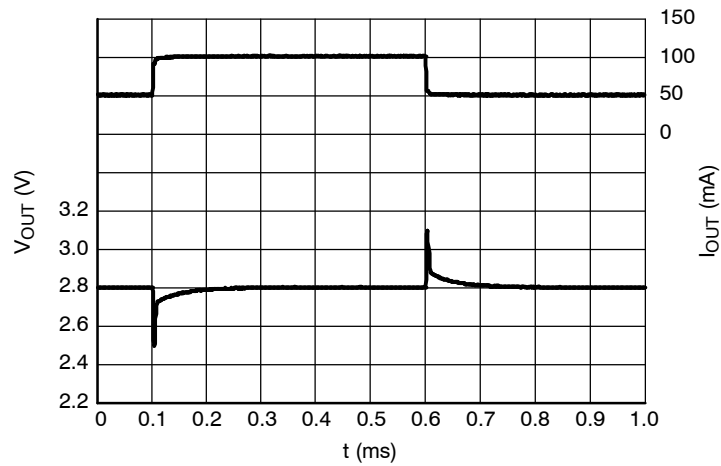
TYPICAL CHARACTERISTICS



**Figure 43. Load Transients, 1.2 V Version,**  
 $I_{OUT} = 50 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 2.2 \text{ V}$

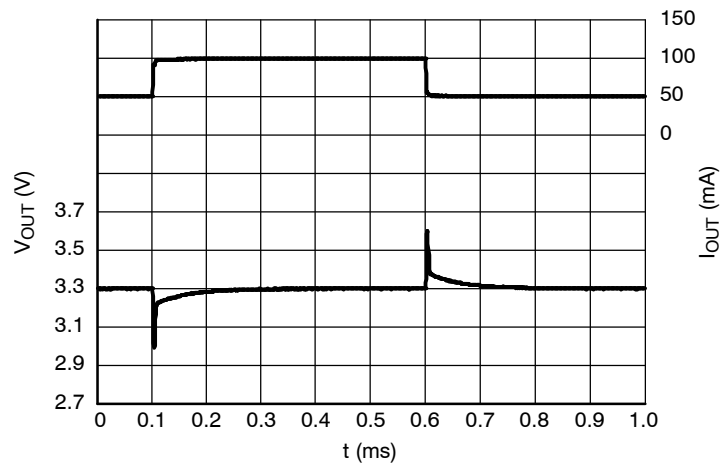


**Figure 44. Load Transients, 2.5 V Version,**  
 $I_{OUT} = 50 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 3.5 \text{ V}$

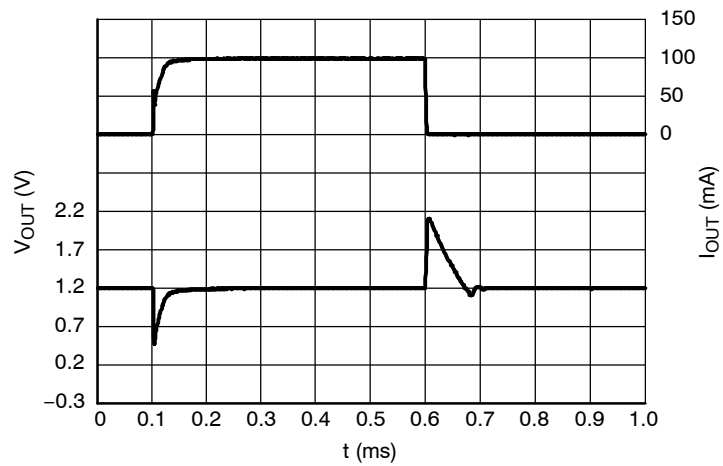


**Figure 45. Load Transients, 2.8 V Version,**  
 $I_{OUT} = 50 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 3.8 \text{ V}$

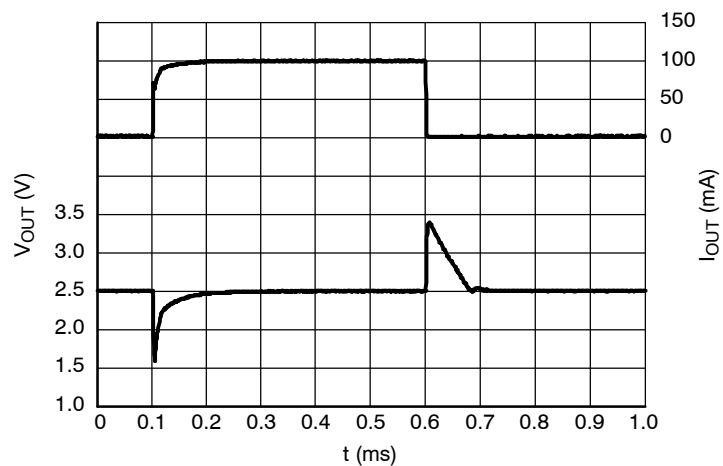
TYPICAL CHARACTERISTICS



**Figure 46. Load Transients, 3.3 V Version,**  
 $I_{OUT} = 50 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 4.3 \text{ V}$



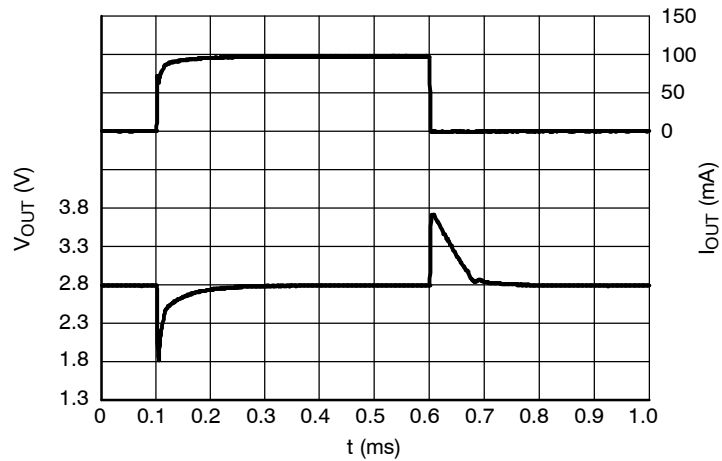
**Figure 47. Load transients, 1.2 V Version,**  
 $I_{OUT} = 1 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 2.2 \text{ V}$



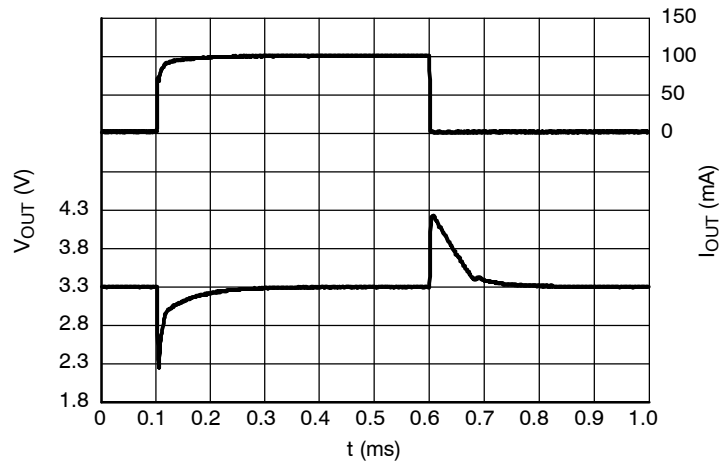
**Figure 48. Load Transients, 2.5 V Version,**  
 $I_{OUT} = 1 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 3.5 \text{ V}$

# NCP4682, NCP4685

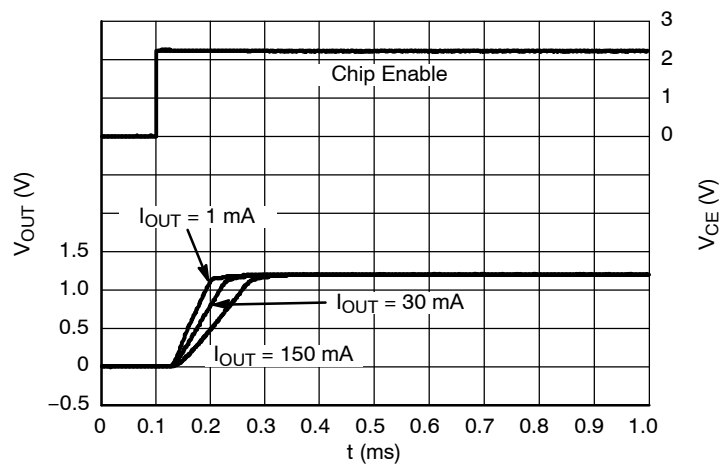
## TYPICAL CHARACTERISTICS



**Figure 49. Load Transients, 2.8 V Version,  
 $I_{OUT} = 1 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 3.8 \text{ V}$**



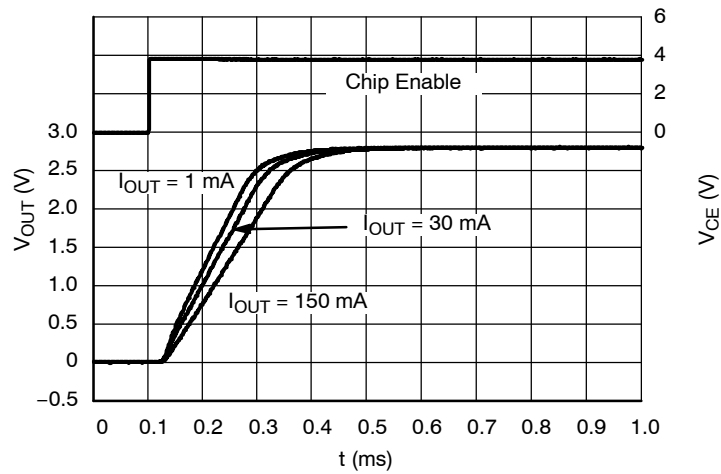
**Figure 50. Load Transients, 3.3 V Version,  
 $I_{OUT} = 1 - 100 \text{ mA}$ ,  $t_R = t_F = 0.5 \mu\text{s}$ ,  $V_{IN} = 4.3 \text{ V}$**



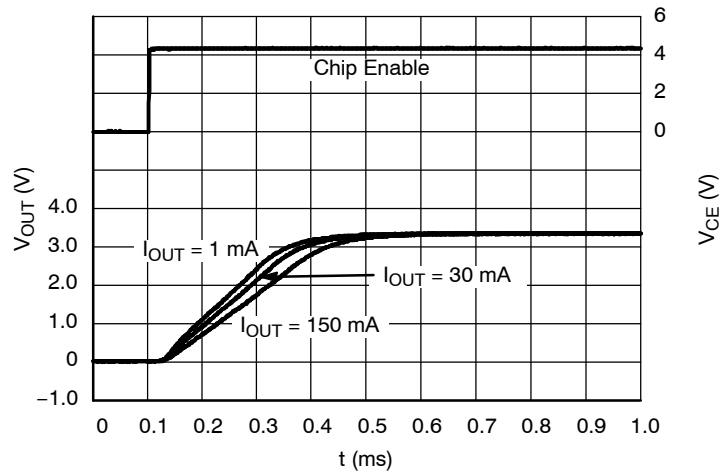
**Figure 51. Start-up, NCP4682 1.2 V Version,  
 $V_{IN} = 2.2 \text{ V}$**

# NCP4682, NCP4685

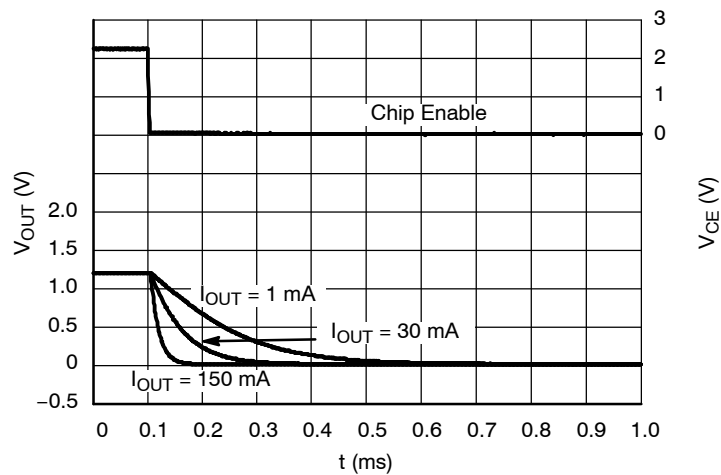
## TYPICAL CHARACTERISTICS



**Figure 52. Start-up, NCP4682 2.8 V Version,  
 $V_{IN} = 3.8 \text{ V}$**

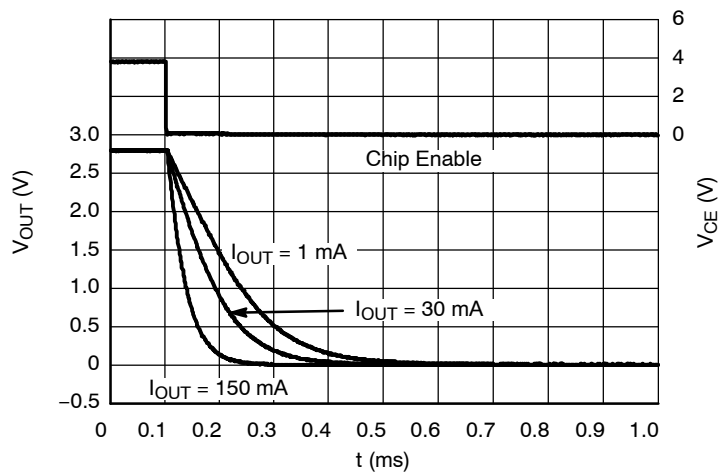


**Figure 53. Start-up, NCP4682 3.3 V Version,  
 $V_{IN} = 4.3 \text{ V}$**

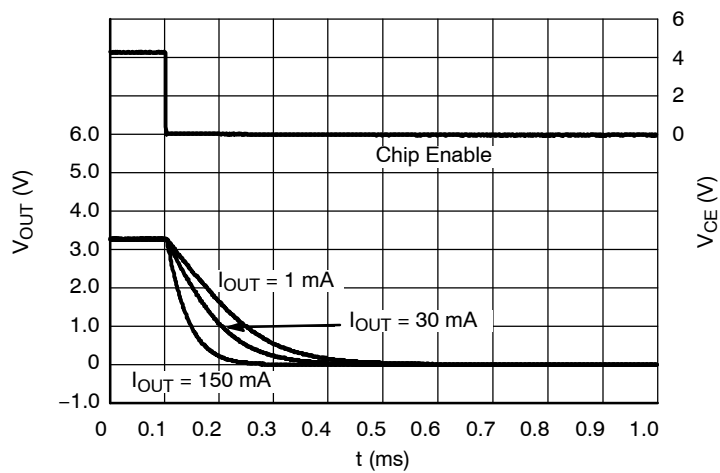


**Figure 54. Shutdown, NCP4682 1.2 V Version D,  
 $V_{IN} = 2.2 \text{ V}$**

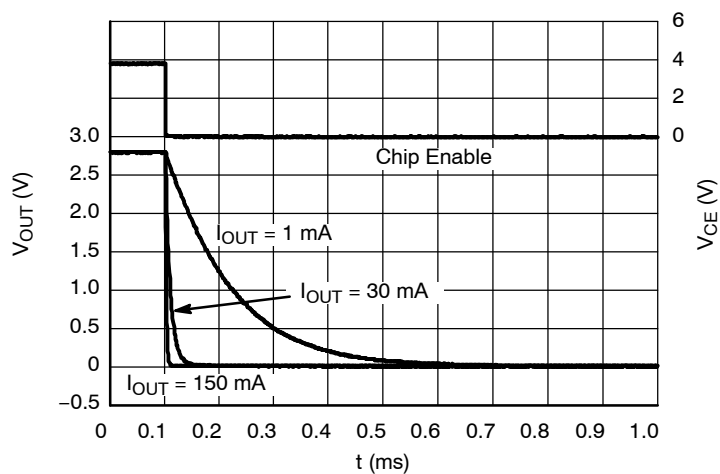
# NCP4682, NCP4685



**Figure 55. Shutdown, NCP4682 2.8 V Version D,  
 $V_{IN} = 3.8$  V**



**Figure 56. Shutdown, NCP4682 3.3 V Version D,  
 $V_{IN} = 4.3$  V**



**Figure 57. Shutdown, NCP4682 2.8 V Version H,  
 $V_{IN} = 3.8$  V**

## APPLICATION INFORMATION

A typical application circuits for NCP4682 and NCP4685 series is shown in Figure 58.

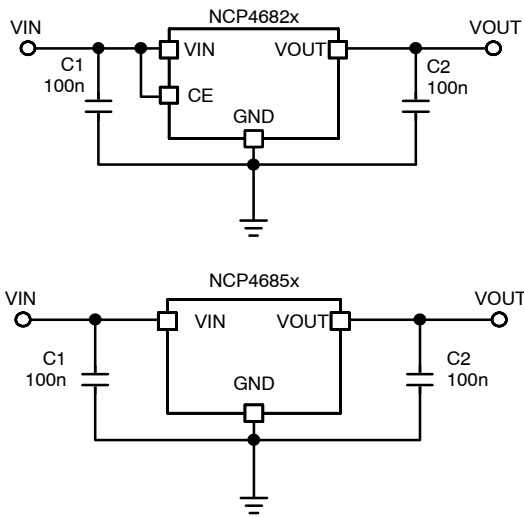


Figure 58. Typical Application Schematic

#### Input Decoupling Capacitor (C1)

A 0.1  $\mu\text{F}$  ceramic input decoupling capacitor should be connected as close as possible to the input and ground pin of the NCP4682/5. Higher values and lower ESR improves line transient response.

#### Output Decoupling Capacitor (C2)

A 0.1  $\mu\text{F}$  ceramic output decoupling capacitor is enough to achieve stable operation of the IC. If a tantalum capacitor is used, and its ESR is high, loop oscillation may result. The capacitors should be connected as close as possible to the output and ground pins. Larger values and lower ESR improves dynamic parameters.

#### Current Limit

This regulator includes a fold-back current limiting circuit. This type of protection doesn't limit output current

up to specified current capability in normal operation, but when an over current situation occurs, the output voltage and current decrease until the over current condition ends. Typical characteristics of this protection scheme are shown in the Output voltage versus Output current graphs in the characterization section of this datasheet.

#### Enable Operation (NCP4682 Only)

The enable pin CE may be used for turning the regulator on and off. The IC is switched on when a high level voltage is applied to the CE pin. The enable pin has an internal pull down current source. If the enable function is not needed, connect CE pin to VIN.

#### Output Discharger (NCP4682 Only)

The NCP4682D version includes a transistor between VOUT and GND that is used for faster discharging of the output capacitor. This function is activated when the IC goes into disable mode.

#### Thermals

As a power across the IC increase, it might become necessary to provide some thermal relief. The maximum power dissipation supported by the device is dependent upon board design and layout. Mounting pad configuration on the PCB, the board material, and also the ambient temperature affect the rate of temperature increase for the part. When the device has good thermal conductivity through the PCB the junction temperature will be relatively low in high power dissipation applications.

#### PCB layout

Make the VIN and GND line as large as practical. If their impedance is high, noise pickup or unstable operation may result. Connect capacitors C1 and C2 as close as possible to the IC, and make wiring as short as possible.

# NCP4682, NCP4685

## ORDERING INFORMATION

| Device          | Nominal Output Voltage | Description    | Marking | Package               | Shipping            |
|-----------------|------------------------|----------------|---------|-----------------------|---------------------|
| NCP4682DMU12TCG | 1.2 V                  | Auto discharge | CA      | UDFN4<br>(Pb-Free)    | 10000 / Tape & Reel |
| NCP4682DMU15TCG | 1.5 V                  | Auto discharge | CC      |                       |                     |
| NCP4682DMU18TCG | 1.8 V                  | Auto discharge | CD      |                       |                     |
| NCP4682DMU19TCG | 1.9 V                  | Auto discharge | CF      |                       |                     |
| NCP4682DMU25TCG | 2.5 V                  | Auto discharge | CH      |                       |                     |
| NCP4682DMU28TCG | 2.8 V                  | Auto discharge | CL      |                       |                     |
| NCP4682DMU30TCG | 3.0 V                  | Auto discharge | CP      |                       |                     |
| NCP4682DMU33TCG | 3.3 V                  | Auto discharge | CR      |                       |                     |
| NCP4682HMU18TCG | 1.8 V                  | Enable high    | AD      |                       |                     |
| NCP4682HMU28TCG | 2.8 V                  | Enable high    | AL      |                       |                     |
| NCP4682HMU33TCG | 3.3 V                  | Enable high    | AR      |                       |                     |
| NCP4685EMU30TCG | 3.0 V                  | Without enable | BP      |                       |                     |
| NCP4682DSN30T1G | 3.0 V                  | Auto discharge | 92P     | SOT-23-5<br>(Pb-Free) | 3000 / Tape & Reel  |
| NCP4682DSN33T1G | 3.3 V                  | Auto discharge | 92R     |                       |                     |
| NCP4682DSQ12T1G | 1.2 V                  | Auto discharge | R0      | SC-82AB<br>(Pb-Free)  | 3000 / Tape & Reel  |
| NCP4682DSQ15T1G | 1.5 V                  | Auto discharge | R2      |                       |                     |
| NCP4682DSQ18T1G | 1.8 V                  | Auto discharge | R3      |                       |                     |
| NCP4682DSQ20T1G | 2.0 V                  | Auto discharge | R6      |                       |                     |
| NCP4682DSQ25T1G | 2.5 V                  | Auto discharge | R7      |                       |                     |
| NCP4682DSQ28T1G | 2.8 V                  | Auto discharge | S0      |                       |                     |
| NCP4682DSQ33T1G | 3.3 V                  | Auto discharge | S5      |                       |                     |
| NCP4685ESQ15T1G | 1.5 V                  | Without enable | N2      |                       |                     |
| NCP4685ESQ25T1G | 2.5 V                  | Without enable | N7      |                       |                     |
| NCP4685ESQ33T1G | 3.3 V                  | Without enable | P5      |                       |                     |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

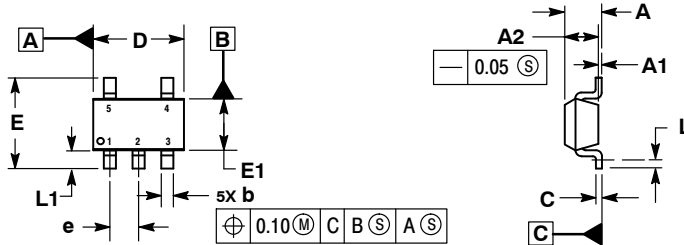
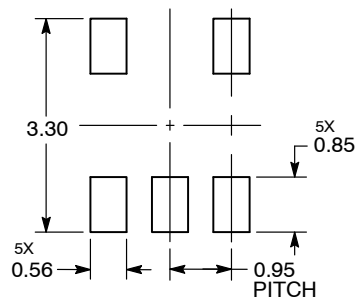
\*To order other package and voltage variants, please contact your ON Semiconductor sales representative.



SCALE 2:1

**SOT-23 5-LEAD**  
**CASE 1212**  
**ISSUE A**

DATE 28 JAN 2011


**RECOMMENDED  
SOLDERING FOOTPRINT\***


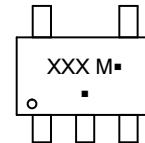
DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DATUM C IS THE SEATING PLANE.

| MILLIMETERS |          |      |
|-------------|----------|------|
| DIM         | MIN      | MAX  |
| A           | ---      | 1.45 |
| A1          | 0.00     | 0.10 |
| A2          | 1.00     | 1.30 |
| b           | 0.30     | 0.50 |
| c           | 0.10     | 0.25 |
| D           | 2.70     | 3.10 |
| E           | 2.50     | 3.10 |
| E1          | 1.50     | 1.80 |
| e           | 0.95 BSC |      |
| L           | 0.20     | ---  |
| L1          | 0.45     | 0.75 |

**GENERIC  
MARKING DIAGRAM\***


XXX = Specific Device Code

M = Date Code

▪ = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

|                         |                      |                                                                                                                                                                                  |
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| <b>DESCRIPTION:</b>     | <b>SOT-23 5-LEAD</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                               |

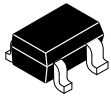
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# MECHANICAL CASE OUTLINE

## PACKAGE DIMENSIONS

ON Semiconductor®

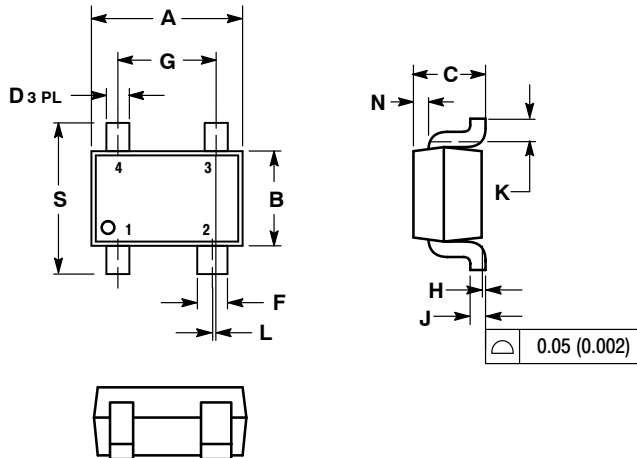
ON



**SC-82AB**  
CASE 419C-02  
ISSUE F

DATE 22 JUN 2012

SCALE 4:1

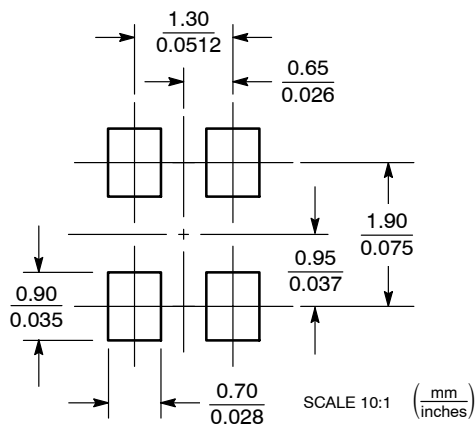


### NOTES:

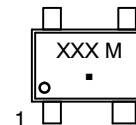
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. 419C-01 OBSOLETE. NEW STANDARD IS 419C-02.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

| DIM | MILLIMETERS |      | INCHES    |       |
|-----|-------------|------|-----------|-------|
|     | MIN         | MAX  | MIN       | MAX   |
| A   | 1.80        | 2.20 | 0.071     | 0.087 |
| B   | 1.15        | 1.35 | 0.045     | 0.053 |
| C   | 0.80        | 1.10 | 0.031     | 0.043 |
| D   | 0.20        | 0.40 | 0.008     | 0.016 |
| F   | 0.30        | 0.50 | 0.012     | 0.020 |
| G   | 1.10        | 1.50 | 0.043     | 0.059 |
| H   | 0.00        | 0.10 | 0.000     | 0.004 |
| J   | 0.10        | 0.26 | 0.004     | 0.010 |
| K   | 0.10        | ---  | 0.004     | ---   |
| L   | 0.05 BSC    |      | 0.002 BSC |       |
| N   | 0.20 REF    |      | 0.008 REF |       |
| S   | 1.80        | 2.40 | 0.07      | 0.09  |

### SOLDERING FOOTPRINT\*



### GENERIC MARKING DIAGRAM\*



XXX = Specific Device Code  
M = Month Code  
■ = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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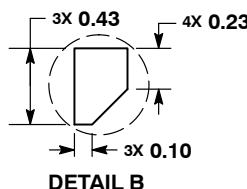
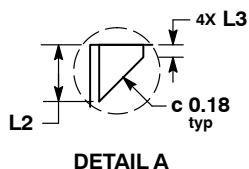
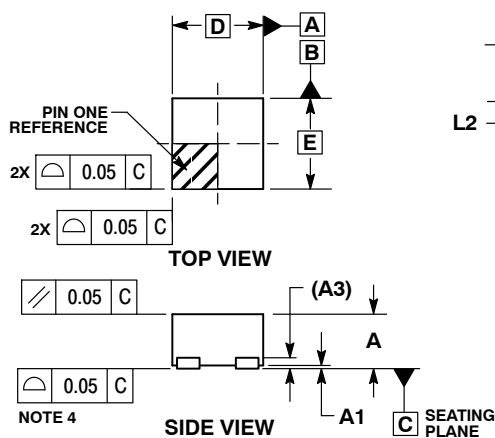
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SCALE 4:1

UDFN4 1.0x1.0, 0.65P  
CASE 517BR-01  
ISSUE O

DATE 27 OCT 2010

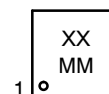


## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 mm FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

| MILLIMETERS |      |      |
|-------------|------|------|
| DIM         | MIN  | MAX  |
| A           | ---  | 0.60 |
| A1          | 0.00 | 0.05 |
| A3          | 0.10 | REF  |
| b           | 0.20 | 0.30 |
| D           | 1.00 | BSC  |
| D2          | 0.43 | 0.53 |
| E           | 1.00 | BSC  |
| e           | 0.65 | BSC  |
| L           | 0.20 | 0.30 |
| L2          | 0.27 | 0.37 |
| L3          | 0.02 | 0.12 |

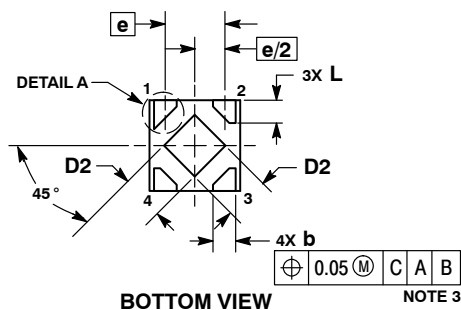
## GENERIC MARKING DIAGRAM\*



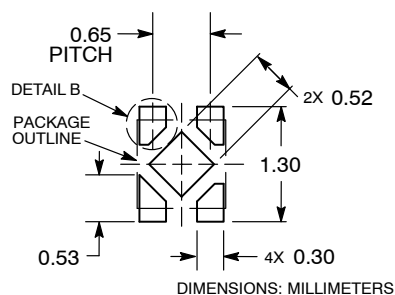
XX = Specific Device Code  
MM = Date Code

\*This information is generic. Please refer to device data sheet for actual part marking.

Pb-Free indicator, "G" or microdot "▪", may or may not be present.



## RECOMMENDED MOUNTING FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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| <b>DESCRIPTION:</b>     | <b>UDFN4, 1.0X1.0, 0.65P</b> | <b>PAGE 1 OF 1</b>                                                                                                                                                                  |

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